

This listing of claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

Claims 1-3 have been canceled.

4. (Previously presented) A method of ~~producing an assembly comprising~~  
electromagnetically screening a printed-circuit electronics card mounted on a metal substrate with a metal screening cover electrically connected to the metal substrate, the method comprising:
  - forming a gutter on the metal-substrate by stamping;
  - mounting the printed circuit electronics card onto a surface of the metal substrate adjacent to the gutter;
  - positioning the metal screening cover having an edge including a tab so that the tab rests substantially within the gutter; and the metal screening cover and said metal substrate together enclose the printed circuit electronics card, and
  - crimping the metal substrate to secure the tab of the metal screening cover onto the metal substrate, wherein the metal screening cover is positioned to be capable of electromagnetically screening the printed circuit electronics card.
5. (Previously presented) A method according to claim 4, wherein the crimping is carried out by localized crushing of a portion of the metal substrate over the tab.
6. (Canceled)

7. (Previously Amended) A method according to claim 4, wherein the tab comprises a plurality of tabs, wherein more than one tab is crimped.